TYAN GT24

B8226

Service Engineer's Manual



PREFACE

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FCC Declaration



Notice for the USA

Compliance Information Statement (Declaration of Conformity Procedure) DoC FCC Part 15: This device complies with part 15 of the FCC Rules

This device complies with Part 15 of the FCC Rules. Operation is subject to the following conditions:

- This device must not cause harmful interference.
- This device must accept any interference received, including interference that may cause undesirable operation.

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

Notice for Canada

This Class A digital apparatus complies with Canadian ICES-003. Cet appareil numérique de la Classe A est conforme à la norme NMB-003 du Canada.



Notice for Europe (CE Mark)

This product is in conformity with the Council Directive 2004/108/EC.

CAUTION: Lithium battery included with this board. Do not puncture, mutilate, or dispose of battery in fire. There will be danger of explosion if battery is incorrectly replaced. Replace only with the same or equivalent type recommended by manufacturer. Dispose of used battery according to manufacturer instructions and in accordance with your local regulations.

About this Manual

This manual provides you with instructions on installing your TYAN GT24-B8226. This Manual is intended for experienced users and integrators with hardware knowledge of personal computers.

This manual consists of the following parts:

Chapter1: Provides an introduction to the TYAN GT24-B8226

barebones, standard parts list, describes the external components, gives a table of key components, and

provides block diagram of the system.

Chapter2: Covers procedures on installing the CPU, memory

modules and hard drives.

Chapter3: Covers removal and replacement procedures for

pre-installed components.

Appendix: List the cable connection and FRU part tables for reference

of system setup, and technical support in case a problem

arises with your system.

Safety and Compliance Information

Before installing and using TYAN GT24-B8226, take note of the following precautions:

- · Read all instructions carefully.
- Do not place the unit on an unstable surface, cart, or stand.
- Do not block the slots and opening on the unit, which are provided for ventilation
- •Only use the power source indicated on the marking label. If you are not sure, contact the power company.
- The unit uses a three-wire ground cable, which is equipped with a third pin to ground the unit and prevent electric shock. Do not defeat the purpose of this pin. If your outlet does not support this kind of plug, contact your electrician to replace your obsolete outlet.
- Do not place anything on the power cord. Place the power cord where it will not be in the way of foot traffic.
- Follow all warnings and cautions in this manual and on the unit case.
- Do not push objects in the ventilation slots as they may touch high voltage components and result in shock and damage to the components.
- When replacing parts, ensure that you use parts specified by the manufacturer.
- When service or repairs have been done, perform routine safety checks to verify that the system is operating correctly.
- Avoid using the system near water, in direct sunlight, or near a heating device.
- · Cover the unit when not in use.

Safety Information

Retain and follow all product safety and operating instructions provided with your equipment. In the event of a conflict between the instructions in this guide and the instructions in equipment documentation, follow the auidelines in the equipment documentation.

Observe all warnings on the product and in the operating instructions. To reduce the risk of bodily injury, electric shock, fire and damage to the equipment, observe all precautions included in this guide.

You must become familiar with the safety information in this guide before you install, operate, or service TYAN products.

Symbols on Equipment

<u> </u>	Caution . This symbol indicates a potential hazard. The potential for injury exists if cautions are not observed. Consult equipment documentation for specific details.
4	Warning. This symbol indicates the presence of hazardous energy circuits or electric shock hazards. Refer all servicing to qualified personnel.
	Warning . This symbol indicates the presence of a hot surface or hot component. If this surface is contacted, the potential for injury exists.
<u> </u>	To reduce risk of injury from a hot component, allow the surface to cool before touching.

General Precautions

 Follow all caution and warning instructions marked on the equipment and explained in the accompanying equipment documentation.

Machine Room Environment

 Make sure that the area in which you install the system is properly ventilated and climate-controlled.

- Ensure that the voltage and frequency of your power source match the voltage and frequency inscribed on the electrical rating label of the equipment.
- Do not install the system in or near a plenum, air duct, radiator, or heat register.
- Never use the product in a wet location.

Equipment Chassis

- Do not block or cover the openings to the system.
- Never push objects of any kind through openings in the equipment. Dangerous voltages might be present.
- Conductive foreign objects can produce a short circuit and cause fire, electric shock, or damage to your equipment.
- · Lift equipment using both hands and with your knees bent.

Equipment Racks

To avoid injury or damage to the equipment:

- Observe local occupational health and safety requirements and guidelines for manual materials handling.
- Do not attempt to move a rack by yourself; a minimum of two people are needed to move a rack.
- Do not attempt to move a fully loaded rack. Remove equipment from the rack before moving it.
- Do not attempt to move a rack on an incline that is greater than 10 degrees from the horizontal.
- Make sure the rack is properly secured to the floor or ceiling.
- Make sure the stabilizing feet are attached to the rack if it is a single-rack installation.
- Make sure racks are coupled together if it is a multiple-rack installation.
- Make sure the rack is level and stable before installing an appliance in the rack.
- Make sure the leveling jacks are extended to the floor.

- · Make sure the full weight of the rack rests on the leveling jacks.
- Always load the rack from the bottom up. Load the heaviest component in the rack first.
- Make sure the rack is level and stable before pulling a component out of the rack.
- Make sure only one component is extended at a time. A rack might become unstable if more than one component is extended.

To avoid damage to the equipment:

- The rack width and depth must allow for proper serviceability and cable management.
- Ensure that there is adequate airflow in the rack. Improper installation or restricted airflow can damage the equipment.
- The rack cannot have solid or restricted airflow doors. You must use a mesh door on the front and back of the rack or remove the doors to ensure adequate air flow to the system.
- If you install the Model in a rack, do not place equipment on top of the unit. It will cause restricted airflow and might cause damage to the equipment.
- Make sure the product is properly matted with the rails. Products that are improperly matted with the rails might be unstable.
- Verify that the AC power supply branch circuit that provides power to the rack is not overloaded. This will reduce the risk of personal injury, fire, or damage to the equipment. The total rack load should not exceed 80 percent of the branch circuit rating. Consult the electrical authority having jurisdiction over your facility wiring and installation requirements.

Equipment Power Cords

- Use only the power cords and power supply units provided with your system. The system might have one or more power cords.
- Plug the power cord into a grounded (earthed) electrical outlet that is easily accessible at all times.
- In all European electrical environments, you must ground the Green/Yellow tab on the power cord. If you do not ground the Green/Yellow tab, it can cause an electrical shock due to high leakage currents.

- Do not place objects on AC power cords or cables. Arrange them so that no one might accidentally step on or trip over them.
- Do not pull on a cord or cable. When unplugging from the electrical outlet, grasp the cord by the plug.
- To reduce the risk of electrical shock, disconnect all power cords before servicing the appliance.

Equipment Batteries

- The system battery contains lithium manganese dioxide. If the battery pack is not handled properly, there is risk of fire and burns.
- Do not disassemble, crush, puncture, short external contacts, or dispose of the battery in fire or water.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- The system battery is not replaceable. If the battery is replaced by an incorrect type, there is danger of explosion. Replace the battery only with a spare designated for your product.
- Do not attempt to recharge the battery.
- Dispose of used batteries according to the instructions of the manufacturer. Do not dispose of batteries with the general household waste. To forward them to recycling or proper disposal, use the public collection system or return them to TYAN, your authorized TYAN partner, or their agents.

Equipment Modifications

• Do not make mechanical modifications to the system. TYAN is not responsible for the regulatory compliance of TYAN equipment that has been modified.

Equipment Repairs and Servicing

- The installation of internal options and routine maintenance and service of this product should be performed by individuals who are knowledgeable about the procedures, precautions, and hazards associated with equipment containing hazardous energy levels.
- Do not exceed the level of repair specified in the procedures in the product documentation. Improper repairs can create a safety hazard.

- Allow the product to cool before removing covers and touching internal components.
- Remove all watches, rings, or loose jewelry when working before removing covers and touching internal components.
- · Do not use conductive tools that could bridge live parts.
- Use gloves when you remove or replace system components; they can become hot to the touch.
- If the product sustains damage requiring service, disconnect the product from the AC electrical outlet and refer servicing to an authorized service provider. Examples of damage requiring service include:
- The power cord, extension cord, or plug has been damaged.
- Liquid has been spilled on the product or an object has fallen into the product.
- The product has been exposed to rain or water.
- The product has been dropped or damaged.
- The product does not operate normally when you follow the operating instructions.

Table of Contents

Chapter	1: Overview	
1.1	About the TYAN GT24-B8226	15
1.2	Product Model	15
1.3	Features	
1.4	Standard Parts List	19
1.4	.1 Box Contents	19
1.4	.2 Accessories	20
1.6	About the Product	
1.6	-,	
1.6	.2 System Rear View	21
1.6		
1.6	· · · · · · · · · · · · · · · · · · ·	
1.6		25
1.6	,	
1.6		
Chapter	2: Setting Up	
2.0	.1 Before you Begin	29
2.0	.2 Work Area	29
2.0	.3 Tools	29
2.0		
2.1	Installing Motherboard Components	
2.1		31
2.1	.2 Installing the CPU and Heatsink	32
2.1	.3 Installing the Memory	35
2.1		
2.1		
2.2		
2.2	3 · · · · · · · · · · · · · · · · · · ·	
2.2		
2.2	.3 Installing the Outer Rails to the Rack	50
2.2		
Chapter	3: Replacing Pre-Installed Components	55
3.1	Introduction	
3.2	Disassembly Flowchart	55
3.3	Removing the Cover	
3.4	Replacing Motherboard Components	
	.1 Replacing Expansion Card	
3.4	.2 Disconnecting All Motherboard Cables	59

Appendix III: Technical Support	85
Appendix II: FRU Parts Table	83
Appendix I: Cable Connection Tables	81
3.9 Replacing the Power Supply	78
3.8.2 M1232/M1235 Connector Pin Definitions	76
3.8.1 M1232/M1235 HDD Backplane Features	73
3.8 Replacing the M1232/M1235 HDD Backplane	70
3.7 Replacing the System Fan	66
3.6.2 M1008 LED Control Board Connector Pin Definition	65
3.6.1 M1008 LED Control Board Features	65
3.6 Replacing the LED Control Board	63
3.5 Replacing the Slim DVD-ROM (optional)	61
3.4.3 Removing the Motherboard	60

Chapter 1: Overview

1.1 About the TYAN GT24-B8226

Congratulations on your purchase of the TYAN® GT24 B8226, a highly optimized rack-mountable barebone system. The GT24 B8226 is designed to support dual AMD® 45nm 4-Core/6-Core Opteron 4100 Series Processors and up to 96GB DDR3-800/1066/1333 memory, providing a rich feature set and incredible performance. Leveraging advanced technology from AMD®, GT24 B8226 server system is capable of offering scalable 32 and 64-bit computing, high bandwidth memory design, and lightning-fast PCI-E bus implementation. The GT24 B8226 not only empowers your company in nowadays IT demand but also offers a smooth path for future application usage.

TYAN[®] also offers the GT24 B8226 in a version that can support up to to four hot-swap hard drives. The GT24 B8226 uses TYAN[®]'s latest chassis featuring a robust structure and a solid mechanical enclosure. All of this provides GT24 B8226 the power and flexibility to meet the needs of nowadays server application.



1.2 Product Model

Model	HDD Bays	Power supply
B8226G24V4H	Hot-swap, 4 HDDs	500 Watts (110/220VAC) Single
B8226G24W4H	Hot-swap, 4 HDDs	500 Watts (110/220VAC) Single

1.3 Features

B8226G24V4	1 H		
	Form Factor	1U Rackmount	
	Chassis Model	GT24	
		25.4" x 17.2" x 1.72" (645 x 436 x 43.6mm)	
System	Motherboard	\$8226GM3NR	
	Board Dimension	EEB, 12"x13" (305x330mm)	
	Gross Weight	12kg (26.54 lbs)	
	Buttons	(1) RST / (1) NMI / (1) ID / (1) PWR w/ LED	
Front Panel	LEDs	(1) ID / (1) Warning / (3) LAN / (1) Reserved	
	I/O Ports	(2) USB ports	
	Type / Q'ty	2.5" or 3.5" Hot-Swap / (4)	
External Drive Bay	Supported HDD	SATA-II 3.0Gb/s /	
Contam Continu	Interface		
System Cooling Configuration	FAN	(5) 4cm fans	
	Туре	EPS1U	
	Efficiency	PFC / 80 plus silver	
Power Supply	Input Range	Full-range AC(100-240V)	
	Frequency	60 Hertz	
	Output Watts	500 Watts	
	Supported CPU Series	AMD 45nm 4-Core/6-Core Opteron 4100 Series Processors (Lisbon)	
Processor	Average CPU Power (ACP) wattage	Up to 80W	
	System Bus	Up to 6.4 GT/s Hyper-Transport link support	
Chipset	Chipset	AMD SR5690 + SP5100	
Chipset	Super I/O	Winbond W83627DHG-P	
	Supported DIMM Qty	(12) DIMM slots	
	DIMM Type / Speed	U/RDDR3 & LV RDDR3, 800/1066/1333 MHz	
Memory	Capacity	Up to 128GB	
	Memory channel	2 Channels per CPU	
	Memory voltage	1.5V or 1.35V	
	PCI-E	(2) PCI-E Gen.2 x16 slots	
Expansion Slots	Pre-install TYAN Riser Card	M2091, PCI-E x16 1U riser card (left) / M2091-R, PCI-E x16 1U riser card (right)	
	Max. HBA Dimension (H x L)	(2) 111.15mm x 167.65mm (FH/HL)	
LAN	Port Q'ty	(3)	
LAN	Controller	Intel 82574L / Intel 82576EB	
	Connector type	D-Sub 15-pin	
Graphic	Resolution	1600x1200@60Hz	
	Chipset	Aspeed AST2050	
	USB	(4) ports (2 at front, 2 at rear)	
I/O Ports	СОМ	(1) DB-9 COM port	
1/O FOILS	VGA	(1) D-Sub 15-pin port	
	RJ-45	(3) ports	
	Chipset	Winbond W83795G	
System	Voltage	Monitors voltage for CPU, memory, chipset & power supply	
Monitoring	Temperature	Monitors temperature for CPU & system environment	
	LED	Over temperature warning indicator / Fan & PSU fail LED indicator	
	Others	Chassis intrusion detection / Watchdog timer support	
	Onboard Chipset	Onboard Aspeed AST2050	
Server Management	AST2050 IPMI Feature	IPMI 2.0 compliant baseboard management controller (BMC) / Supports storage over IP and remote platform-flash / BIOS update	
		24-bit high quality video compression / Dual 10/100 Mb/s MAC interfaces	
BIOS	Brand / ROM size	AMI / 4MB	

	Feature	Plug and Play (PnP) /PCI2.3 /WfM2.0 /SMBIOS2.3 /PXE boot / ACPI 2.0 power management /Power on mode after power recovery / User-configurable H/W monitoring / Auto-configurable of hard disk type		
Operating System	OS supported list	Please visit out Web site for the latest OS supported list.		
Regulation	FCC (DoC)	Class A		
Regulation	CE (DoC)	Yes		
	Operating Temp.	10° C ~ 35° C (50° F~ 95° F)		
Operating	Non-operating Temp.	- 40° C ~ 70° C (-40° F ~ 158° F)		
Environment	In/Non-operating Humidity	90%, non-condensing at 35° C		
RoHS	RoHS 6/6 Complaint	Yes		
	Barebone	(1) GT24B8236 Barebone		
	Manual	(1) MB User's manual + (1) BB User's manual		
	Installation CD	(1) TYAN installation CD		
Package Contains	Heatsink / Cooler	(2) 1207-pin CPU heatsinks		
Package Contains	Rail kit	(1) CRAL-0031, sliding rail kit for KGT24/ KGT62		
	Mounting Ear	(1) mounting ear kit		
	Cable Power Cord	(1) CCBL-0310, US type power cord / (1) CCBL-0300, EU type power cord		
	Other	(1) slim type CD/DVD-ROM Bracket with screw kit		
Optional accessories	Peripheral	(1) CDVD-0060, slim type DVD-ROM		

System	B8226G24W	4H		
Dimension (D x W x H) 25.4" x 17.2" x 1.72" (645 x 436 x 43.6mm)		Form Factor	1U Rackmount	
Motherboard S8226WGM3NR Board Dimension EEB, 12"x13" (305x330mm) System Board Dimension EEB, 12"x13" (305x330mm) System Suttons (1) RST / (1) NMI / (1) ID / (1) PWR w/ LED		Chassis Model	GT24	
Motherboard S8226WCM3NR Board Dimension EEB, 12"x13" (305x330mm) Gross Weight 12kg (26.54 lbs) Buttons (1) RST / (1) NMI / (1) ID / (1) PWR w/ LED Front Panel LEDs (1) ID / (1) Warning / (3) LAN / (1) Reserved I/O Ports (2) USB ports Type / Q'ty 2.5" or 3.5" Hot-Swap / (4) External Drive Bay Supported HDD Interface SATA-II 3.0Gb/s /SAS 6.0Gb/s System Cooling Configuration FAN (5) 4cm fans Type	Cuetom	Dimension (D x W x H)	25.4" x 17.2" x 1.72" (645 x 436 x 43.6mm)	
Gross Weight 12kg (26.54 lbs)	System	Motherboard	<u>S8226WGM3NR</u>	
Front Panel		Board Dimension	EEB, 12"x13" (305x330mm)	
Front Panel LEDs I/O Ports I/O Ports (2) USB ports Type / Q'ty External Drive Bay Supported HDD Interface SATA-II 3.0Gb/s /SAS 6.0Gb/s System Cooling Configuration Type Efficiency PFC / 80 plus silver Fan (5) 4cm fans Fan (5) 4cm fans Fyequency Frequency Find Horts Supported CPU Series Average CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Chipset Supported DIMM Qty DIMM Type / Speed U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Memory Memory Capacity Up to 1.85G Memory voltage PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser Card Max. HBA Dimension (2) 111.15mm x 167 65mm (EH/HI) (2) USB ports (2) USB ports (2) USB ports (4) USA NA / (1) Reserved (4) Reserved (4) Exerved (4) Exerved (4) Exerved (4) Exerved (4) Exerved (5) 4cm fans (6) 4cm fans (6) 4cm fans (6) 4cm fans (7) 111.15mm x 167 65mm (EH/HI)		Gross Weight	12kg (26.54 lbs)	
I/O Ports (2) USB ports Type / Q'ty 2.5" or 3.5" Hot-Swap / (4) External Drive Bay Supported HDD Interface SATA-II 3.0Gb/s /SAS 6.0Gb/s System Cooling Configuration FAN (5) 4cm fans Type EPS1U Efficiency PFC / 80 plus silver Input Range Full-range AC(100-240V) Frequency 60 Hertz Output Watts 500 Watts Supported CPU Series AMD 45nm 4-Core/6-Core Opteron 4100 Series Processors (Lisbon) Processor Average CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Chipset Supported DIMM Qty (12) DIMM slots DIMM Type / Speed U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Capacity Up to 128GB Memory channel 2 Channels per CPU Memory voltage PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser Cripht) Max. HBA Dimension (2) 111 15 mm x 167 65 mm (FH/HII)		Buttons	(1) RST / (1) NMI / (1) ID / (1) PWR w/ LED	
Type / Q'ty 2.5" or 3.5" Hot-Swap / (4) SATA-II 3.0Gb/s /SAS 6.0Gb/s System Cooling Configuration Type Efficiency PFC / 80 plus silver Frequency Go Hertz Output Watts 500 Watts Supported CPU Series Average CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Chipset Chipset AMD SR5690 + SP5100 Supported DIMM Qty DIMM Qty DIMM Type / Speed U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Memory Capacity Up to 128GB Memory voltage PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser Card Max. HBA Dimension (2) 111 15mm x 167 65mm (EH/HI)	Front Panel	LEDs	(1) ID / (1) Warning / (3) LAN / (1) Reserved	
External Drive Bay Supported HDD Interface System Cooling Configuration FAN System Cooling FAN Type Efficiency PC / 80 plus silver Frequency Output Watts Supported CPU Series Average CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Chipset Chipset Supported DIMM Qty DIMM Type / Speed Up to 128 GB Memory channel Among System Supported DIMM System Capacity Memory voltage Memory voltage Expansion Slots Expansion Slots FAN (5) 4cm fans PC / 80 plus silver PC / 80 plu		I/O Ports	(2) USB ports	
System Cooling Configuration			2.5" or 3.5" Hot-Swap / (4)	
Type EPS1U Efficiency PFC / 80 plus silver Power Supply Input Range Full-range AC(100-240V) Frequency 60 Hertz Output Watts 500 Watts Supported CPU Series AMD 45nm 4-Core/6-Core Opteron 4100 Series Processors (Lisbon) Processor Average CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Chipset AMD SR5690 + SP5100 Super I/O Winbond W83627DHG-P Supported DIMM Qty (12) DIMM slots DIMM Type / Speed U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Capacity Up to 128GB Memory channel 2 Channels per CPU Memory voltage 1.5V or 1.35V PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser Cripht) Max. HBA Dimension (2) 111 15 mm x 167 65 mm (FH/HI)	External Drive Bay		SATA-II 3.0Gb/s /SAS 6.0Gb/s	
Power Supply Input Range Frequency Output Watts Supported CPU Series Average CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Chipset AmD SR5690 + SP5100 Super I/O Supported DIMM Qty DIMM Type / Speed U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Memory Among CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Up to 80W (12) DIMM Salots Up to 128GB Memory channel Among Capacity Up to 128GB Memory voltage 1.5V or 1.35V Pre-install TYAN Riser Card Max. HBA Dimension (2) 111 15mm x 167 65mm (EH/HL)		FAN	(5) 4cm fans	
Power Supply Frequency Output Watts Supported CPU Series AMD 45nm 4-Core/6-Core Opteron 4100 Series Processors (Lisbon) Processor Average CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Chipset AMD SR5690 + SP5100 Winbond W83627DHG-P Supported DIMM Qty DIMM Type / Speed U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Memory Memory voltage Pre-install TYAN Riser Card Max. HBA Dimension Frequency 60 Hertz 500 Watts 60 Hertz 60 Watts 60 Hertz 60 Hertz 60 Watts 60 Hertz 60 Hertz 60 Hertz 60 Hort 60 H		Туре	EPS1U	
Frequency Output Watts Supported CPU Series AMD 45nm 4-Core/6-Core Opteron 4100 Series Processors (Lisbon) Average CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Chipset AMD SR5690 + SP5100 Super I/O Super I/O Winbond W83627DHG-P Supported DIMM Qty (12) DIMM slots U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Capacity Up to 128GB Memory channel 2 Channels per CPU Memory voltage PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser Card Max. HBA Dimension (2) 111 15mm x 167 65mm (EH/HL)		Efficiency	PFC / 80 plus silver	
Output Watts Supported CPU Series	Power Supply	Input Range	Full-range AC(100-240V)	
Supported CPU Series AMD 45nm 4-Core/6-Core Opteron 4100 Series Processors (Lisbon)		Frequency	60 Hertz	
Processor Average CPU Power (ACP) wattage System Bus Up to 6.4 GT/s Hyper-Transport link support Chipset Chipset Super I/O AMD SR5690 + SP5100 Super I/O Winbond W83627DHG-P Supported DIMM Qty DIMM Type / Speed U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Memory Capacity DIMM Type / Speed U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Memory channel Memory voltage 2 Channels per CPU Memory voltage 1.5V or 1.35V PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser Card (right) M2091, PCI-E x16 1U riser card (left) / M2091-R, PCI-E x16 1U riser card (right) Max. HBA Dimension (2) 111 15 mm x 167 65 mm (FH/HII)		Output Watts	500 Watts	
Chipset Chipset Chipset Chipset Chipset Chipset Super I/O Winbond W83627DHG-P		Supported CPU Series	AMD 45nm 4-Core/6-Core Opteron 4100 Series Processors (Lisbon)	
Chipset Chipset Super I/O AMD SR5690 + SP5100 Winbond W83627DHG-P Memory Supported DIMM Qty DIMM Subsets (12) DIMM slots U/RDDR3 & LV RDDR3, 800/1066/1333 MHz Memory Capacity Up to 128GB Memory channel 2 Channels per CPU Memory voltage 1.5V or 1.35V PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser Card (right) R2091, PCI-E x16 1U riser card (left) / M2091-R, PCI-E x16 1U riser card (right) Max. HBA Dimension (2) 111 15 mm x 167 65 mm (EH/HII)	Processor		Up to 80W	
Super I/O Winbond W83627DHG-P		System Bus	Up to 6.4 GT/s Hyper-Transport link support	
Super I/O Winbond W83627DHG-P	Chinset	Chipset	AMD SR5690 + SP5100	
DIMM Type / Speed	Cimpoct	Super I/O	Winbond W83627DHG-P	
Memory Capacity Up to 128GB Memory channel 2 Channels per CPU Memory voltage 1.5V or 1.35V PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser M2091, PCI-E x16 1U riser card (left) / M2091-R, PCI-E x16 1U riser card (right) Max. HBA Dimension (2) 111 15 mm x 167 65 mm (FH/HL)		Supported DIMM Qty	(12) DIMM slots	
Memory channel 2 Channels per CPU		DIMM Type / Speed	U/RDDR3 & LV RDDR3, 800/1066/1333 MHz	
Memory voltage 1.5V or 1.35V PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser M2091, PCI-E x16 1U riser card (left) / M2091-R, PCI-E x16 1U riser card (right) Max. HBA Dimension (2) 111 15mm x 167 65mm (EH/HL)	Memory	Capacity	Up to 128GB	
PCI-E (2) PCI-E Gen.2 x16 slots Pre-install TYAN Riser Card (left) / M2091-R, PCI-E x16 1U riser card (right) Max. HBA Dimension (2) 111 15mm x 167 65mm (FH/HL)		Memory channel	2 Channels per CPU	
Expansion Slots Pre-install TYAN Riser Card (M2091, PCI-E x16 1U riser card (left) / M2091-R, PCI-E x16 1U riser card (right) Max. HBA Dimension (2) 111 15mm x 167 65mm (FH/HL)		Memory voltage		
Expansion Slots Card (right) Max. HBA Dimension (2) 111 15mm x 167 65mm (FH/HI)		PCI-E	(2) PCI-E Gen.2 x16 slots	
(2) 111 15mm v 167 65mm (FH/HI)	Expansion Slots			
			(2) 111.15mm x 167.65mm (FH/HL)	

LAN	Port Q'ty	(3)
LAN	Controller	Intel 82574L / Intel 82576EB
	Connector type	D-Sub 15-pin
Graphic	Resolution	1600x1200@60Hz
	Chipset	Aspeed AST2050
	USB	(4) ports (2 at front, 2 at rear)
I/O Ports	СОМ	(1) DB-9 COM port
1/O Ports	VGA	(1) D-Sub 15-pin port
	RJ-45	(3) ports
	Chipset	Winbond W83795G
	Voltage	Monitors voltage for CPU, memory, chipset & power supply
System Monitoring	Temperature	Monitors temperature for CPU & system environment
Homeoring	LED	Over temperature warning indicator / Fan & PSU fail LED indicator
	Others	Chassis intrusion detection / Watchdog timer support
	Onboard Chipset	Onboard Aspeed AST2050
Server Management	AST2050 IPMI Feature	IPMI 2.0 compliant baseboard management controller (BMC) / Supports storage over IP and remote platform-flash / BIOS update
	AST2050 iKVM Feature	24-bit high quality video compression / Dual 10/100 Mb/s MAC interfaces
	Brand / ROM size	AMI / 4MB
BIOS	Feature	Plug and Play (PnP) /PCI2.3 /WfM2.0 /SMBIOS2.3 /PXE boot / ACPI 2.0 power management /Power on mode after power recovery / User-configurable H/W monitoring / Auto-configurable of hard disk types
Operating System	OS supported list	Please visit out Web site for the latest OS supported list.
Regulation	FCC (DoC)	Class A
Regulation	CE (DoC)	Yes
	Operating Temp.	10° C ~ 35° C (50° F~ 95° F)
Operating	Non-operating Temp.	- 40° C ~ 70° C (-40° F ~ 158° F)
Environment	In/Non-operating Humidity	90%, non-condensing at 35° C
RoHS	RoHS 6/6 Complaint	Yes
	Barebone	(1) GT24B8236 Barebone
	Manual	(1) MB User's manual + (1) BB User's manual
Package Contains	Installation CD	(1) TYAN installation CD
	Heatsink / Cooler	(2) 1207-pin CPU heatsinks
	Rail kit	(1) CRAL-0031, sliding rail kit for KGT24/ KGT62
	Mounting Ear	(1) mounting ear kit
	Cable Power Cord	(1) CCBL-0310, US type power cord / (1) CCBL-0300, EU type power cord
	Other	(1) slim type CD/DVD-ROM Bracket with screw kit
Optional accessories	Peripheral	(1) CDVD-0060, slim type DVD-ROM

1.4 Standard Parts List

This section describes GT24-B8226 package contents and accessories. Open the box carefully and ensure that all components are present and undamaged. The product should arrive packaged as illustrated below.

1.4.1 Box Contents

Component	Description
	1U chassis,(4) hot swap HDDbays
	TYAN [®] S8226 system board (pre-installed)
Name of the second seco	500W single Power Supply
	(5) 40x28mm System FAN (pre-installed)
TO THE STATE OF TH	M1008: LED control board (pre-installed)
	M1232/M1235 SATA/SAS HDD Backplane
	M2091 PCI-E riser card
	M2091-R PCI-E riser card

1.4.2 Accessories

If any items are missing or appear damaged, contact your retailer or browse to TYAN®'s website for service: http://www.tyan.com

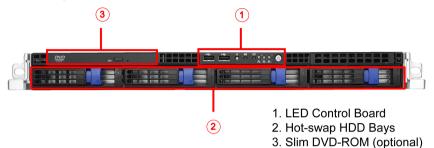
The web site also provides information of other TYAN® products, as well as FAQs, compatibility lists, BIOS settings, etc.

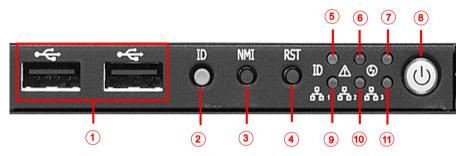


1.6 **About the Product**

The following views show you the product.

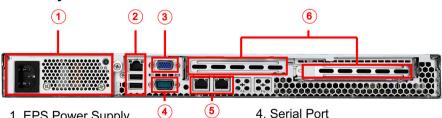
System Front View 1.6.1





- 1. USB Ports
- 2. ID Button
- 3. NMI Button
- 4. Reset Button
- 5. ID LED
- 6. Warning LED
- 7. BMC LED (reserved)
- 8. Power Button (with LED)
- 9. NIC1
- 10. NIC2
- 11. NIC3

1.6.2 **System Rear View**



- 1. EPS Power Supply
- 2. LAN3 (share with IPMI) + 2 USB Ports
- 3. VGA Port
- 5. LAN2 (left) + LAN1 (right)
- 6. 2 PCI-E Slots

1.6.3 LED Definitions

Front Panel

LED	State	Color	Description
	On	Green	System is turned on
Power LED	Blinking	Green	System is under S1 or S3 state
	Off	Off	Power off
	Blinking	Green	LAN active
NIC1	On	Green	LAN linked
	off	off	LAN not linked
	Blinking	Green	LAN active
NIC2	On	Green	LAN linked
	off	off	LAN not linked
	Blinking	Green	LAN active
NIC3	On	Green	LAN linked
	off	off	LAN not linked
Warning LED	On	Red	Fan fail /Over temperature /Over voltage
	Off	Off	No failure
IDLED	On	Blue	System identified
ID LED	Off	Off	System not identified

Rear I/O

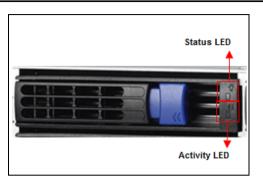
LAN LED

LED	State	Color	Description
D 1.45	On	Green	10Mb/100Mb/1000Mb linked
RJ-45 Activity(left)	Blinking	Green	10Mb/100Mb/1000Mb activity
	Off	Off	No LAN linked
RJ-45 Linkage(Right)	On	Amber	1000Mb linked
	On	Green	100Mb linked
Linkago(rtight)	Off	Off	10Mb mode or No LAN linked

NOTE: "Left" and "Right" are viewed from the rear panel.

ID LED

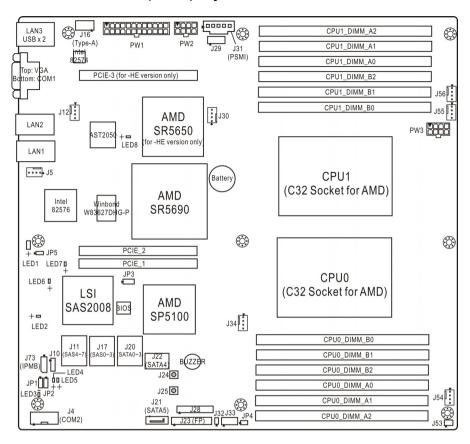
LED	State	Color	Description
ID LED	On	Blue	System identified
I ID LED	Off	Off	System not identified



HDD LED

HDD Status		Status LED 2/4/6/8 Color: Amber	Activity LED 1/3/5/7 Color: Green
No Driver Present or power disconnected		OFF	OFF
Driver Present	No Activity	OFF	ON
	Access Activity	OFF	Blinking
HDD Fail		On Solid	OFF
Identify (Locate the HDD)		Blinking(1Hz)	OFF
SAS/SATA RAID Building		Blinking(4Hz)	OFF

1.6.4 Motherboard (S8226) Layout



The diagram is representative of the latest board revision available at the time of publishing. The board you receive may not look exactly like the above diagram.

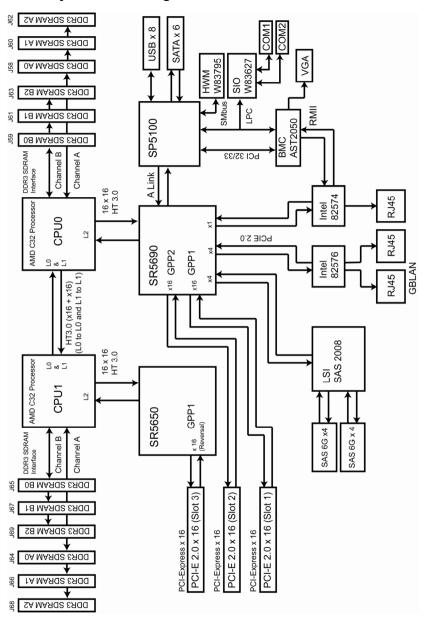
1.6.5 Jumpers & Connectors

Jumper/Connector	Function
J4	COM2 Header
J5/J12/J30/J34/J54/J55/J56	4-pin Fan Connectors
J10	Port 80 Header (reserved)
J23	Front Panel Header
J24	Reset Switch
J25	Power Switch
J28	Fan TACH Connector
J29/J33	USB Front Panel Header
J31	PSMI Connector
J32	LAN3 Active LED Header
J53	HDD Fault Header
J73	IPMB Header
JP1/JP2	COM2 Function Select Jumper
JP3	Clear CMOS Jumper
JP4	Chassis Intrusion Header
JP5	Front Panel ID LED Header
LED1	ID LED
LED2	SAS Flash Ready (Amber)
LED3	SAS HD Fault LED (Amber)
LED4	Power On LED (Green)
LED5	Standby LED (Green)
LED6	SAS Error LED (Amber)
LED7	SAS Heart Beat LED (Green)
LED8	BMC Heart Beat LED (Green)

Jumper Legend

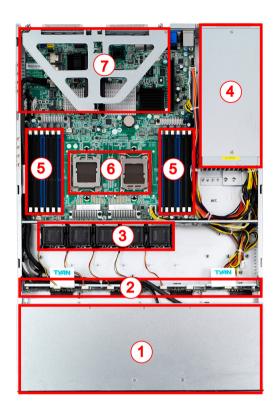
OPEN - Jumper OFF	Without jumper cover
CLOSED - Jumper ON	With jumper cover

1.6.6 System Block Diagram



26 http://www.tyan.com

1.6.7 Internal View



1	HDD Cage
2	M1232/M1235 HDD Backplane
3	System Fans
4	500W Power Supply
5	Memory Slots
6	CPU Sockets
7	PCI-E Riser Card Assembly

NOTE

Chapter 2: Setting Up

2.0.1 Before you Begin

This chapter explains how to install the CPUs, CPU heatsinks, memory modules, and hard drives. Instructions on inserting add on cards are also given.

2.0.2 Work Area

Make sure you have a stable, clean working environment. Dust and dirt can get into components and cause malfunctions. Use containers to keep small components separated. Putting all small components in separate containers prevents them from becoming lost. Adequate lighting and proper tools can prevent you from accidentally damaging the internal components.

2.0.3 Tools

The following procedures require only a few tools, including the following:

- A cross head (Phillips) screwdriver
- A grounding strap or an anti-static pad

Most of the electrical and mechanical connections can be disconnected with your hands. It is recommended that you do not use pliers to remove connectors as it may damage the soft metal or plastic parts of the connectors.

2.0.4 Precautions

Components and electronic circuit boards can be damaged by discharges of static electricity. Working on a system that is connected to a power supply can be extremely dangerous. Follow the guidelines below to avoid damage to GT24-B8226 or injury to yourself.

- Ground yourself properly before removing the top cover of the system. Unplug the power from the power supply and then touch a safely grounded object to release static charge (i.e. power supply case). If available, wear a grounded wrist strap. Alternatively, discharge any static electricity by touching the bare metal chassis of the unit case, or the bare metal body of any other grounded appliance.
- Avoid touching motherboard components, IC chips, connectors, memory modules, and leads.
- The motherboard is pre-installed in the system. When removing the motherboard, always place it on a grounded anti-static surface until you are ready to reinstall it.
- Hold electronic circuit boards by the edges only. Do not touch the components on the board unless it is necessary to do so. Do not flex or stress circuit boards.
- Leave all components inside the static-proof packaging that they ship with until they are ready for installation.
- After replacing optional devices, make sure all screws, springs, or other small parts are in place and are not left loose inside the case.
 Metallic parts or metal flakes can cause electrical shorts.

NOTE: All connectors are keyed to only attach one way. All use the correct screw size as indicated in the procedures.

2.1 Installing Motherboard Components

This section describes how to install components on to the mainboard, including CPUs, memory modules and add on cards.

2.1.1 Removing the Chassis Cover

Follow these instructions to remove GT24-B8226 chassis cover.

1. Unscrew the rear top cover on the back side as shown in the small diagram.



2. Slide the rear top cover out.



2.1.2 Installing the CPU and Heatsink

Follow the steps below on installing CPUs and CPU heatsinks.

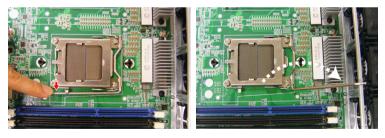
1. Locate the CPU socket.



2. Take off the protection cap.



3. Pull the lever slightly away from the socket and then push it to a fully open position.



4. Push the CPU socket cover to a fully open position.



5. Place the CPU into the socket and make sure that the gold arrow is located in the right direction.

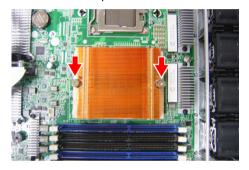


6. Close the CPU socket cover and press the lever down to secure the CPU.





7. Position the heatsink on top of the CPU and secure it with 2 screws.



8. Repeat the procedures mentioned earlier to install the second CPU and heatsink.

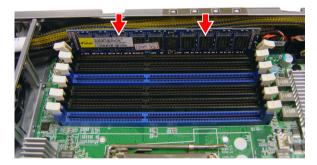
2.1.3 Installing the Memory

Follow these instructions to install the memory modules onto the motherboard.

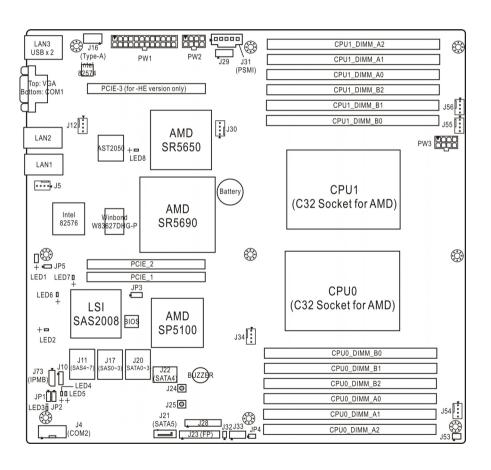
- **1.** Locate the memory slots on the motherboard.
- **2.** Press the memory slot locking levers in the direction of the arrows as shown in the following illustration.



3. Align the memory module with the slot. When inserted properly, the memory slot locking levers lock automatically onto the indentations at the ends of the module. Follow the recommended memory population table to install the other memory modules.







36 http://www.tyan.com

Recommended Memory Population Table

R-DIMM Module Support

DDR3 Spe	ed/Voltage	DDR	Max GB /		
1.35v	1.5v	DIMM0 (A0, B0)	DIMM1 (A1, B1)	DIMM2 (A2, B2)	Channel
667MHz	667MHz	SR or DR	QR	SR or DR	32GB
667MHz	800MHz	n/a	QR	SR or DR	24GB
800MHz	800MHz	DR	SR or DR	SR or DR	24GB
800MHz	800MHz	n/a	QR	n/a	16GB
1066MHz	1066MHz	DR	n/a	SR or DR	16GB
800MHz	1066MHz	SR	SR	SR	12GB
1333MHz	1333MHz	SR	n/a	SR	8GB
1333MHz	1333MHz	n/a	n/a	SR or DR	8GB

- RDIMM can support up to 16GB sized DIMM's
- SR and DR Memory has a MAX amount of 24GB per channel
- QR Memory has a MAX amount of 32GB per channel
- QR 1.35v Memory MAX speed of 667MHz in a dual channel configuration
- SR: Single-rank, DR: Dual-rank, QR:Quad-rank

Single-Rank & Dual-Rank Memory Module											
	Single CPU Dual CPU Installed installed (CPU0 only) (CPU0 and CPU1)										
Quantity of memory installed	1	2	4	6	2	3	4	6	8	10	12
CPU0_DIMM(1)B0			√	√				$\sqrt{}$	$\sqrt{}$	$\sqrt{}$	√
CPU0_DIMM(2)B1				√						√	√
CPU0_DIMM(3)B2		√	√	1		√	√	√	√	√	√
CPU0_DIMM(4)A0			V	√				√	√	√	√
CPU0_DIMM(5)A1				1						√	√
CPU0_DIMM(6)A2	√	V	√	√	√	$\sqrt{}$	$\sqrt{}$	$\sqrt{}$	$\sqrt{}$	$\sqrt{}$	√
CPU1_DIMM(7)B0									V	V	√
CPU1_DIMM(8)B1											√
CPU1_DIMM(9)B2							√	√	√	√	1
CPU1_DIMM(10)A0									√	√	√
CPU1_DIMM(11)A1											1
CPU1_DIMM(12)A2					√	√	√	√	√	√	√

- 1. $\sqrt{\text{indicates a populated DIMM slot.}}$
- 2. Paired memory installation for Max performance.
- 3. Populate the same DIMM type in each channel, specifically
 - Use the same DIMM size
 - Use the same # of ranks per DIMM
- 4. Dual-rank DIMMs are recommended over single-rank DIMMs.
- 5. We don't suggest other memory installation.

Single-Rank, Dual-Rank & Quad-Rank Memory Module											
	Single CPU Installed (CPU0 only)							al CPU stalled and CP	U1)		
Quantity of memory installed	1	2	4	6	2	3	4	6	8	10	12
CPU0_DIMM(1)B0				SR/DR						SR/DR	SR/DR
CPU0_DIMM(2)B1		QR	QR	QR		QR	QR	QR	QR	QR	QR
CPU0_DIMM(3)B2			SR/DR	SR/DR				SR/DR	SR/DR	SR/DR	SR/DR
CPU0_DIMM(4)A0				SR/DR						SR/DR	SR/DR
CPU0_DIMM(5)A1	QR	QR	QR	QR	QR	QR	QR	QR	QR	QR	QR
CPU0_DIMM(6)A2			SR/DR	SR/DR				SR/DR	SR/DR	SR/DR	SR/DR
CPU1_DIMM(7)B0											SR/DR
CPU1_DIMM(8)B1							QR	QR	QR	QR	QR
CPU1_DIMM(9)B2									SR/DR	SR/DR	SR/DR
CPU1_DIMM(10)A0											SR/DR
CPU1_DIMM(11)A1					QR	QR	QR	QR	QR	QR	QR
CPU1_DIMM(12)A2									SR/DR	SR/DR	SR/DR

U-DIMM Module Support

DDR3 Spe	ed/Voltage	DDR3	Max GB/		
1.35v	1.5v	DIMM0 (A0, B0)	DIMM1 (A1, B1)	DIMM2 (A2, B2)	Channel
1066MHz	1066MHz	DR	n/a	SR or DR	8GB
1333MHz	1333MHz	SR	n/a	SR	4GB
1333MHz	1333MHz	n/a	n/a	SR or DR	4GB

- U-DIMM can support up to 4GB sized DIMM's
- Maximum of 8GB per channel
- SR and DR UDDR3 module support only
- x8 DRAM module support only
- SR: Single-rank, DR: Dual-rank, QR: Quad-rank

		Single CPU Installed (CPU0 only)		Dual CPU Installed (CPU0 and CPU1)			
Quantity of memory installed	1	2	4	2	4	6	8
CPU0_DIMM(1)B0			√				√
CPU0_DIMM(2)B1							
CPU0_DIMM(3)B2		√	√		1	1	1
CPU0_DIMM(4)A0			√				1
CPU0_DIMM(5)A1							
CPU0_DIMM(6)A2	√	√	√	V	√	√	√
CPU1_DIMM(7)B0							√
CPU1_DIMM(8)B1							
CPU1_DIMM(9)B2						√	√
CPU1_DIMM(10)A0							1
CPU1_DIMM(11)A1							
CPU1_DIMM(12)A2				√	1	1	√

- 1. √ indicates a populated DIMM slot.
- 2. Paired memory installation for Max performance.
- 3. Populate the same DIMM type in each channel, specifically
 - Use the same DIMM size
 - Use the same # of ranks per DIMM
- 4. Dual-rank DIMMs are recommended over single-rank DIMMs
- 5. Unbuffered DIMM can offer slightly better performance than registerd DIMM if populating only a single DIMM per channel.
- 6. We don't suggest other memory installation.
- 7. AMD 4100 series CPU doesn't support Quad-ranks U-DIMM.

2.1.4 Installing Hard Drives

The GT24-B8226 supports four 3.5" hard drives. Follow these instructions to install a hard drive.

1. Press the locking lever latch and pull the locking lever open.



2. Slide the HDD tray out.



3. Remove the 6 screws.



4. Place a hard drive into the drive tray.



5. Use 6 HDD screws to secure the HDD.



6. Reinsert the HDD tray into the chassis and press the locking lever to secure the tray.



2.1.5 Installing the PCI-E Cards

The GT24-B8226 supports one PCI-E expansion slot. Follow these instructions to install the PCI-E card.

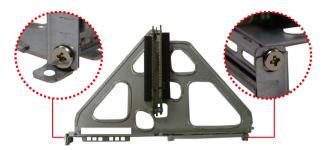
1. Unscrew the riser card bracket from the chassis.



2. Lift the front edge of the riser card bracket first before taking it out from the chassis.



3. Release the screws on both sides of the riser card bracket as shown.



4. Remove the PCI-E cover shields from the chassis.



5. Insert the PCI-E card in the direction of arrows as shown.



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6. Screw the PCI-E cards firmly to the riser card bracket.



7. Secure the riser card bracket to the chassis with two screws.



8. The installation of PCI-E expansion card is now complete.

2.2 Rack Mounting

After installing the necessary components, the TYAN GT24-B8226 can be mounted in a rack using the supplied rack mounting kit.

Rack mounting kit

- Sliding Rails x 2
- Sliding Brackets x 4 (Front x 2, Rear x 2)
- Mounting Ears (including screws) x 2
- Screws Kit x 1
- Mounting Brackets x 4

2.2.1 Installing the Server in a Rack

Follow these instructions to mount the TYAN GT24-B8226 into an industry standard 19" rack.

NOTE: Before mounting the TYAN GT24-B8226 in a rack, ensure that all internal components have been installed and that the unit has been fully tested.

Screws List

	No.	Screw	Size	Quantity
Rail Kit	А	(M4-4L	18
	В		M5-8L	10
	С		M5-15	4
Mounting Ear Kit	D		#6-32 L5.3	4

2.2.2 Installing the inner Rails to the Chassis

1. Screw the mounting ear to each side of TYAN GT24-B8226 as shown using two screws of #6-32 L5.3(D) from the supplied screws kit.

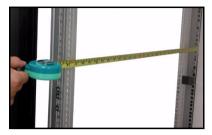


2. Draw out the inner rails from rail assembly. Install inner rails to left and right sides of chassis using 1 M4-4L(A) screw for each side.



2.2.3 Installing the Outer Rails to the Rack

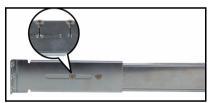
1. Measure the distance between inner side of the front and rear mounting brackets in the rack.



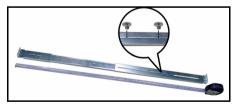
2. Locate the front and rear brackets.



3. Secure the front bracket to outer rail with 2 M4-4L(A) screws.



4. Reserve the distance same as in Step 2 on rear bracket. Secure the rear bracket to outer rail with 2 M4-4L(A) screws.



5. Secure the outer rail to the rack using 2 brackets and 4 M5-8L(B) screws for each side. Secure the mounting brackets from inside, not outside, of the rack.

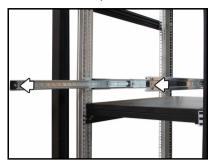


Mounting Bracket



2.2.4 Rack mounting the Server

1. Draw out the middle rail to the latch position.



2. Lift the chassis and then insert the inner slide rails into the middle rails.

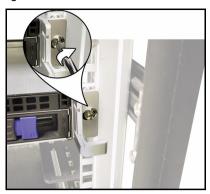


3. Push the chassis in and press the latch key (A). Then push the whole system into the rack (B) $\,$





4. Secure the mounting ears of chassis to the rack with 2 M5-15L(C) screws.



NOTE: To avoid injury, it is strongly recommended that two people lift the TYAN GT24-B8226 into the place while a third person screws it to the rack.

NOTE

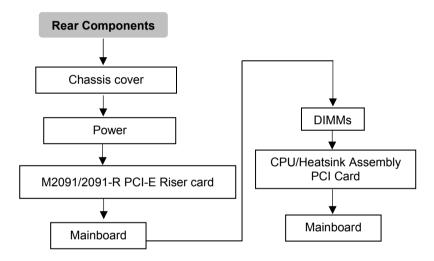
Chapter 3: Replacing Pre-Installed Components

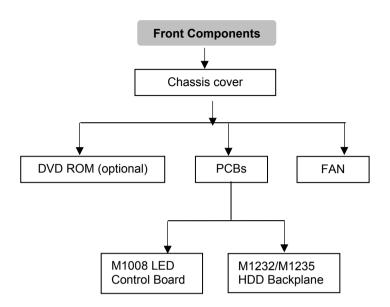
3.1 Introduction

This chapter explains how to replace the pre-installed components, including the Motherboard, M1008 LED control board, M1232/M1235 HDD Backplane, M2091/M2091-R PCI-E Riser card, System fan, ODD drive, Power supply unit etc.

3.2 Disassembly Flowchart

The following flowchart outlines the disassembly procedure.





3.3 Removing the Cover

Before replacing any parts you must remove the chassis cover first. Follow **Chapter 2.1.1** to remove the cover of the GT24-B8226.

3.4 Replacing Motherboard Components

Follow these instructions to replace motherboard components, including the motherboard.

3.4.1 Replacing Expansion Card

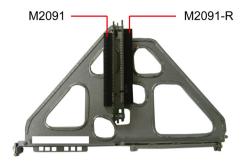
The GT24-B8226 has **two preinstalled PCI-E ×16** riser cards, Follow the instructions below to disassemble the M2091/M2091-R PCI-E riser cards.

1. Unscrew to remove the riser card bracket from the chassis.









2. Unscrew the M2091 riser card.



3. Unscrew the M2091-R riser card.



4. Install a new riser card onto the bracket following the procedures mentioned earlier in reverse order.

3.4.2 Disconnecting All Motherboard Cables

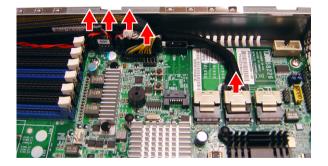
Before replacing the motherboard or certain components, remove cables connected to the motherboard. Follow these instructions to remove all motherboard cables.

1. Disconnect all power cables.





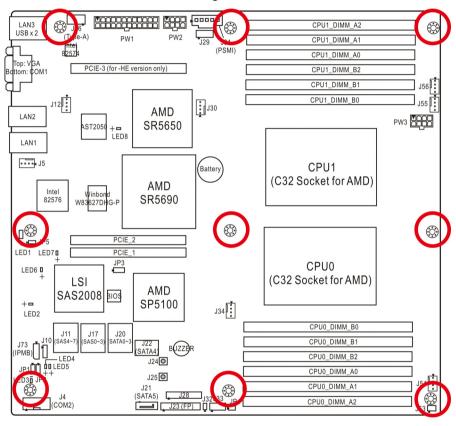
2. Disconnect all other cables.



3.4.3 Removing the Motherboard

After removing all of the aforementioned cables, follow the instructions below to remove the motherboard from the chassis.

- 1. Remove the heatsinks and processors if installed.
- 2. Remove the nine screws securing the motherboard to the chassis.



3. Carefully lift the motherboard from the chassis.

3.5 Replacing the Slim DVD-ROM (optional)

Follow these instructions to replace the slim DVD-ROM.

1. Remove the power and data cable from the slim DVD-ROM adapter.



2. Press the tab in the directions as shown to release the DVD-ROM drive.



3. The DVD-ROM drive will be freed from the drive bay after pressing the tab.



4. Disconnect the power and data cables from the DVD-ROM drive.



5. Remove two screws that secure DVD-ROM drive to the bracket.



- 6. Replace the DVD-ROM drive.
- 7. Secure DVD-ROM to the bracket using two screws. Then replace the unit into the drive bay and connect the DVD-ROM power and data cables.

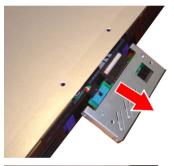
3.6 Replacing the LED Control Board

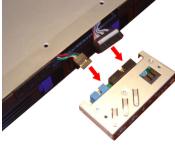
Follow these instructions to replace the M1008 LED control board.

1. Remove the two screws securing the LED control board unit to the chassis.



2. Push the LED control board unit out and unplug the cables from the connectors at the back of the unit.

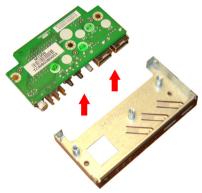




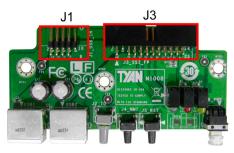
3. Remove three screws securing the LED control board to the bracket.



4. Lift the LED control board free from the chassis. After replacing the LED control board, insert the unit into the chassis following the above procedures in reverse



3.6.1 M1008 LED Control Board Features



M1008 Front Panel Board (FPB) to S8226								
M1008 Connect to S8226								
Control Cable	J3	\rightarrow	J23+J32					
USB Cable	J1	\rightarrow	J33					

3.6.2 M1008 LED Control Board Connector Pin Definition

J1: USB Header

702 ::0440:							
Definition	Pin	Pin	Definition				
VCC	1	2	VCC				
USB1-	3	3 4 USB2-					
USB1+	5	6	USB2+				
GND	7	7 8 GND					
Key	9	10	GND				

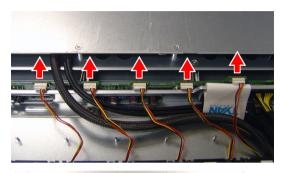
J3: <u>SSI</u>

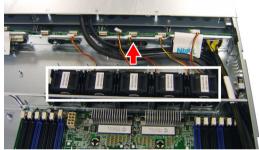
Definition	Pin	n Pin Definition	
PW_LED+	1	2	VCC
KEY	3	4	ID_LED+
PW_LED-	5	6	ID_LED-
HD/LAN3 LED+	7	8	SYS_FAULT1-
HD/LAN3 LED-	9	10	SYS_FAULT2-
PWR_SW+	11	12	LAN1_LED+
PWR_SW-	13	14	LAN1_LED-
RESET+	15	16	ICH_SMBDAT
RESET-	17	18	ICH_SMBCLK
ID_SW+	19	19 20 INTRU#	
TEMP_SENSER	21 22 LAN2_LED+		LAN2_LED+
EXT_INT	23	24	LAN2_LED-

3.7 Replacing the System Fan

Follow these instructions to replace the cooling fans in your system.

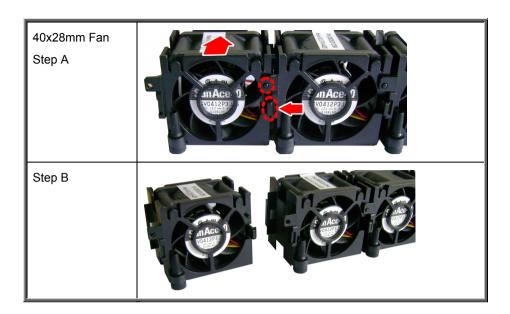
- 1. Locate the cooling fans in your system.
- 2. Unplug the cables connected to the mainboard and lift the fan unit up from the chassis.



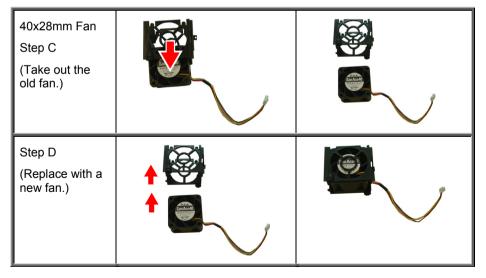


3. Follow Step A & B to unlock the fans.



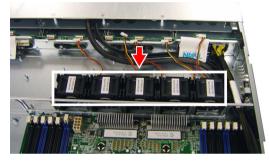


4. Follow Step C & D to take out the old fan and replace with a new one.



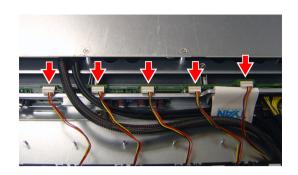
5. After replacing the new fans, follow Step A & B in reverse order to lock the fans. Reinstall the fans into the chassis.





6. Connect the fan cables to the backplane fan connectors.

S	System Fan to M1232/M1235									
System Fan	System Fan Connect to M1232/M1235									
Fan1	\rightarrow	Fan2								
Fan2	\rightarrow	Fan3								
Fan3	\rightarrow	Fan4								
Fan4	\rightarrow	Fan5								
Fan5	\rightarrow	Fan6								



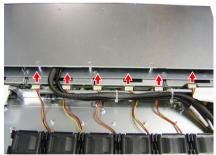
3.8 Replacing the M1232/M1235 HDD Backplane

1. Disconnect the power cables connected to the HDD Backplane.

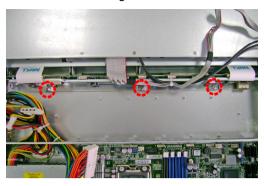


2. Disconnect the Mini SAS cable and the fan cables.

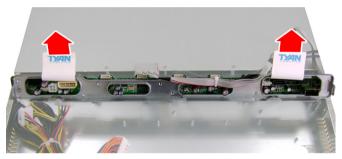




3. Remove the three screws securing the bracket to the chassis base.



4. Lift the bracket up from the chassis.



5. Unscrew the HDD Backplane from the bracket.



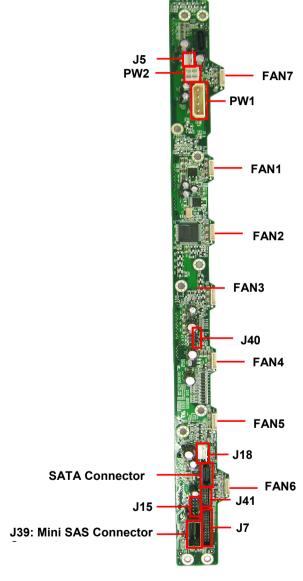
6. Replace a new HDD Backplane and reinstall it into the chassis following the steps mentioned earlier in reverse.

M1232/M1235 SATA/SAS Backplane to S8226WGM3NR								
Cable SATA/SAS BP Connect to S8226 MB								
Mini-SAS Cable	J39	\rightarrow	J17 (SAS 0 ~ 3)					
Fan Cable	J7	\rightarrow	J28					

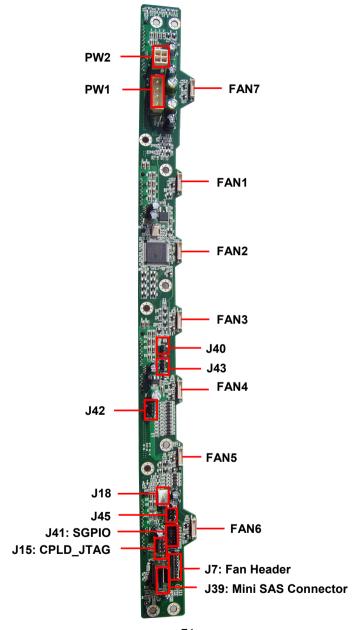
M1232/M1235 SATA/SAS Backplane to S8226GM3NR								
Cable SATA/SAS BP Connect to S8226 MB								
Mini-SAS Cable	J39	\rightarrow	J20 (SATA 0 ~ 3)					
Fan Cable	J7	\rightarrow	J28					

3.8.1 M1232/M1235 HDD Backplane Features

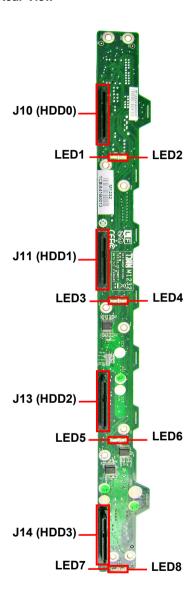
M1232 Front View



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75 http://www.tyan.com

3.8.2 M1232/M1235 Connector Pin Definitions

PW1

Pin	1	2	3	4
Definition	+12V	GND	GND	+5V

PW2

Definition	Pin	Pin	Definition
GND	1	2	GND
+12V	3	4	+12V

J15 SGPIO JTAG

Definition	Pin	Pin	Definition
TCK	1	2	GND
TDO	3	4	3.3V
TMS	5	6	NI
NI	7	8	KEY
TDI	9	10	GND

J41 SGPIO for IOH

Definition	Pin	Pin	Definition
SM_CLK	1	2	SGPIO_0
SM_DATA	3	4	SGPIO_1
GND	5	6	SGPIO_2
KEY	7	8	SGPIO_3
NI	9	10	HD_ERR_LED

J5 Slim Hard Disk power (M1232 only)

Pin	1	2	3	4
Definition	+12V	GND	GND	+5V

J18 Slim CDROM power

Pin	1	2	3	4
Definition	+12V	GND	GND	+5V

J45 SMBus Header

Definition	Pin	Pin	Definition
SMBUS2_3V3_DATA	1	2	SMBUS2_3V3_CLK
SMBUS2_DATA	3	4	SMBUS2_CLK
GND	5	6	GND

J40 PWM Control Jumper

Pin	Definition	
1	CPU_PWM	
2	PWM_12	
3	CPU_PWM2	

Pin 1-2 closed: (Default)

J43 SGPIO Jumper Switch

Pin	Definition	
1	+3V3	
2	STRAPO	
3	GND	

Pin 1-2 closed: for Intel Platform

Pin 2-3 closed: for AMD Platform & LSI SAS Controller (Default)

J42 (Reserved)

Pin	Definition	
1	+3V3	
2	STRAP1	
3	GND	

Pin 1-2 closed: (Default)

3.9 Replacing the Power Supply

1. Disconnect the power cables from the motherboard and the M1232.



PSU to M1232/M1235 Backplane (BP) Board					
PSU Connect to M1232/M1235					
2x2P PWR P3	\rightarrow	PW2			
B4P P4 → PW1					





78 http://www.tyan.com

PSU to S8226 MB						
Power Supply Unit (PSU)	Connect to	S8226				
2x12P PWR P1	\rightarrow	J18				
2x4P PWR P2	\rightarrow	J26				
2x4P PWR P7	\rightarrow	J52				
PSMI P8	\rightarrow	J31				

2. Remove nine (9) screws that secure the power supply to the chassis.





3. Remove the power supply bracket and then slide out the whole power supply unit.





4. Install a new power supply unit following the steps in reverse.

Appendix I: Cable Connection Tables

1. System Fan Connector

System Fan to M1232/M1235 Backplane (BP) Board				
System Fan	System Fan Connect to M1232/M12			
Fan1	\rightarrow	FAN2		
Fan2	\rightarrow	FAN3		
Fan3	\rightarrow	FAN4		
Fan4	\rightarrow	FAN5		
Fan5	\rightarrow	FAN6		

2. SATA HDD Cable

M1232/M1235 SATA/SAS Backplane (BP) Board to S8226 MB				
Cable	M1232	Connect to	S8226 MB	
Mini-SAS Cable	J39	\rightarrow	J20 (S8226GM3NR) J17 (S8226WGM3NR)	
Fan cable	J7	\rightarrow	J28	

3. Control Cable and USB Cable

M1008 LED Control Board to S8226 MB						
	M1008 Connect to S8226 MB					
Control Cable	J3	\rightarrow	J23+J32			
USB Cable	J1	\rightarrow	J33			

4. Power Supply Cables

PSU to S8226 MB			
Power Supply Unit (PSU)	Connect to	S8226	
2x12P PWR P1	\rightarrow	J18	
2x4P PWR P2	\rightarrow	J26	
2x4P PWR P7	\rightarrow	J52	
PSMI P8	\rightarrow	J31	

PSU to M1232/M1235 Backplane (BP) Board			
PSU	Connect to	M1232/M1235	
2x2P PWR P3	\rightarrow	PW2	
B4P P4	\rightarrow	PW1	

5. Chassis Intrusion Cable

Chassis Intrusion Cable			
Chassis	Connect to	S8226 MB	
Intrusion Cable	\rightarrow	JP4	

Appendix II: FRU Parts Table

GT24-B8226 FRU Parts					
Item	Model Number	Part Number	Picture	Quantity	Description
Power Supply	CPSU-0520	471015200263		1	500W single Power Supply
FAN	CFAN-0241	336252012294		6	14700RPM,40*40*28MM
Heatsink & Cooler	CHSK-0320	343769000004		2	AMD C32 1U Passive Heatsink
PCBA	M2091	1	Programme CFS VI	1	PCI-E X16 1U Riser Card(Left)
	M2091-R	1	O (C RE UI O DA SILVIII O	1	PCI-E X16 1U Riser Card (Right)
	CRAL-0031	452783400001		1	Slide Rail Kit
Rack Mounting Part	CRAL-0150	340740900010	8 8 8 8	1	Mounting Ear Kit
	CCBL-067O	422784300005			Mini-SAS to Mini-SAS Cable, 400mm
Cable Set	CCBL-0317	332810000397		1	A/C Power Cord, L=1800mm,US type
	CCBL-0300	332810000281		1	A/C Power Cord, L=1830mm,EU type

NOTE

Appendix III: Technical Support

If a problem arises with your system, you should first turn to your dealer for direct support. Your system has most likely been configured or designed by them and they should have the best idea of what hardware and software your system contains. Hence, they should be of the most assistance for you. Furthermore, if you purchased your system from a dealer near you, take the system to them directly to have it serviced instead of attempting to do so yourself (which can have expensive consequence).

If these options are not available for you then MiTAC International Corporation can help. Besides designing innovative and quality products for over a decade, MiTAC has continuously offered customers service beyond their expectations. TYAN's website (http://www.tyan.com) provides easy-to-access resources such as in-depth Linux Online Support sections with downloadable Linux drivers and comprehensive compatibility reports for chassis, memory and much more. With all these convenient resources just a few keystrokes away, users can easily find their latest software and operating system components to keep their systems running as powerful and productive as possible. MiTAC also ranks high for its commitment to fast and friendly customer support through email. By offering plenty of options for users, MiTAC serves multiple market segments with the industry's most competitive services to support them.

TYAN's tech support is some of the most impressive we've seen, with great response time and exceptional organization in general." — Anandtech.com

Please feel free to contact us directly for this service at tech-support@tyan.com

Help Resources:

- See the TYAN's website for FAQ's, bulletins, driver updates, and other information: http://www.tyan.com
- 2. Contact your dealer for help before calling TYAN.
- 3. Check the TYAN user group: alt.comp.periphs.mainboard.TYAN

Returning Merchandise for Service

During the warranty period, contact your distributor or system vendor FIRST for any product problems. This warranty only covers normal customer use and does not cover damages incurred during shipping or failure due to the alteration, misuse, abuse, or improper maintenance of products.

NOTE:

A receipt or copy of your invoice marked with the date of purchase is required before any warranty service can be rendered. You may obtain service by calling the manufacturer for a Return Merchandise Authorization (RMA) number. The RMA number should be prominently displayed on the outside of the shipping carton and the package should be mailed prepaid.

TYAN will pay to have the board shipped back to you.

TYAN® GT24-B8226 Service Engineer's Manual V1.0a

Document No.: <u>D2100-100</u>